

Chemistry and Band Offsets of HfO₂ Thin Films for ULSI Gate Insulators

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Introduction

High-k dielectric materials have attracted much attention since physically thicker dielectric films are strongly required to create a very thin equivalent oxide thickness for sub 0.1 μm ULSI devices. Although various metal oxides with high dielectric constants have been proposed, HfO₂ has been regarded as one of the most promising candidates among them because of its high dielectric constant, high resistivity, and high thermal stability. So far many spectroscopic studies¹ have been done on the interfacial chemistry including silicate formation and band offsets for the HfO₂/Si system using photoelectron spectroscopy. The precise information about chemical states and band offsets, however, for the complicated HfO₂/silicate/Si system where the silicate interlayer formation is hardly prevented has not been obtained mainly due to insufficient energy resolution of X-ray photoelectron spectroscopy. In this study, therefore, the interfacial chemistry and band offsets of HfO₂ films grown on Si(100) substrates have been investigated using high resolution angle-resolved photoelectron spectroscopy.

Experimental

HfO₂ films with 4.4 nm and 7.5 nm thicknesses were grown by reactive sputtering of Hf metal with the oxygen ambient on p-Si(100) substrates. The thicknesses of HfO₂ films were measured by cross-sectional transmission electron microscope (TEM) and the compositions of the films were determined by energy dispersive x-ray (EDX) analysis. To determine the CET (capacitance equivalent thickness), C-V characteristics were measured. High-resolution synchrotron radiation photoelectron spectroscopy (SRPES) was performed with a Gammatdata-Scienta SES100 electron analyzer with photon energies ranging from 330 eV to 800 eV at an undulator beamline 2C of the Photon Factory in KEK.

Results and discussion

A cross-sectional TEM image of the 4.4 nm HfO₂ film grown on Si(100) revealed a double layer structure with a 1.6 nm-thick upper layer and a 2.8 nm-thick lower layer, probably a Hf_{1-x}Si_xO₂ layer. C-V characteristics revealed that the CET for the 4.4 nm film was 2.6 nm. Figures 1(a) and (b) show Hf 4f photoelectron spectra from the HfO₂/Hf_{1-x}Si_xO₂/Si(100) samples with the oxide thicknesses of 4.4 nm and 7.5 nm, respectively. On the contrary, the Hf 4f spectrum from the 7.5 nm thick sample which has a very thin Hf_{1-x}Si_xO₂ interlayer with

only 0.5 nm thickness is well fitted with only one component of Hf 4f, as shown in Fig. 2(b). It is also found that there is no Hf-silicide component at the interface. The similar chemical shift features were observed for O 1s spectrum. The O 1s spectrum can be well fitted with three chemical states, namely HfO₂, Hf_{1-x}Si_xO₂ at 1.3 eV shift and the unknown component at 2.5 eV shift.

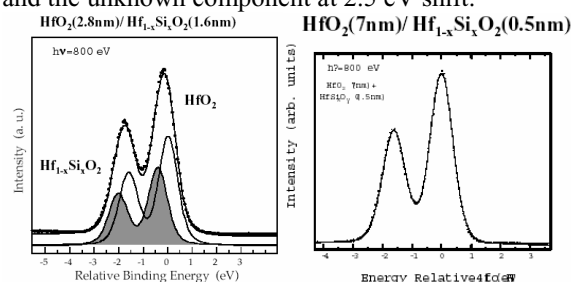


Fig. 1. Hf 4f photoelectron spectra from Hf_{1-x}Si_xO₂/Si (4.4 nm and 7.5 nm thick).

Next, we attempted to directly determine valence band offsets. The valence band maximum (VBM) was determined by extrapolating the valence band of Si. Since the measured valence band is composed of valence bands of HfO₂, Hf_{1-x}Si_xO₂ and Si, it is quite difficult to directly determine band offsets. In order to subtract the contribution from the Si substrate, we measured the valence band of a clean Si substrate. From these subtracted spectra, it is possible to determine valence band offsets to be 3.0 eV and 3.8 eV for HfO₂/Si and Hf_{1-x}Si_xO₂/Si, respectively.² In order to determine the band alignment, O 1s energy loss spectra were also measured. The extrapolated values from the O 1s energy loss spectra for the 4.4 nm and 7.5 nm films are 5.2 eV which can be regarded as the band gap of HfO₂. The band gap of 5.2 eV for HfO₂ and the valence band offset of 3.0 eV for HfO₂/Si lead to the conduction band offset for HfO₂/Si to be 1.1 eV, which is slightly smaller than 1.5 eV reported by Robertson.³

In conclusion, the interfacial chemistry and band offsets of HfO₂ films grown on Si are investigated using high resolution angle-resolved photoelectron spectroscopy, and are well correlated with interfacial structures revealed by cross-sectional TEM and C-V measurements.

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References

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